

Title (en)
METHOD FOR PRODUCING A COMPOSITE PART AND COMPOSITE PART

Title (de)
VERFAHREN ZUM HERSTELLEN EINES VERBUNDTEILS UND VERBUNDTEIL

Title (fr)
PROCEDE DE PRODUCTION D'UNE PIECE COMPOSITE, ET PIECE COMPOSITE

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Application
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Abstract (en)
[origin: DE19741924A1] The invention relates to a method for producing a composite part consisting of a component and a glass plate (10). According to said method, a body (1) formed by a semiconductor substrate is brought into contact with the glass plate (10) and an electric voltage is applied between the body (1) and the glass plate (10), said voltage been high enough to move the ions contained in the glass plate (10). Before the body (1) and the glass plate (10) are assembled, a connecting layer (8) containing silicon is applied on the body (1). Before the connection layer (8) is applied, at least one additional layer (2) is formed in or applied on the body (1) and doping agents are implanted on the additional layer (2).

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